PRODUCT / PROCESS CHANGE NOTIFICATION

1. PCN basic data

1.1 Company	STMicroelectronics International N.V
1.2 PCN No.	POWER AND DISCRETE PRODUCTS/25/15213
1.3 Title of PCN	Mold Compound replacement and FE Process improvement (Industrial).
1.4 Product Category	Pls refer to SIC MOSFET products list.
1.5 Issue date	2025-02-18

2. PCN Team

2.1 Contact supplier	
2.1.1 Name	PIKE EMMA
2.1.2 Phone	+44 1628896111
2.1.3 Email	emma.pike@st.com
2.2 Change responsibility	
2.2.1 Product Manager	Angelo RAO
2.1.2 Marketing Manager	Antonino GAITO
2.1.3 Quality Manager	Vincenzo MILITANO

3. Change

3.1 Category	**3.2 Type of change**	**3.3 Manufacturing Location**
Materials	Direct Material: Mold compound - Chemistry (raw material)	SH1A---ST SHENZHEN -CHINA

4. Description of change

	Old	**New**
4.1 Description	Kyocera G300S-1 as molding compound and Single passivation and Square TEOS.	Sumitomo G720EH as molding compound and Round Teos and Double Passivation.
4.2 Anticipated Impact on form,fit, function, quality, reliability or processability?	Impact on processability	

5. Reason / motivation for change

5.1 Motivation	Discontinuation of KYOCERA KEG-300S-1 production and FE process improvement.
5.2 Customer Benefit	SERVICE CONTINUITY

6. Marking of parts / traceability of change

6.1 Description	by dedicated FGs

7. Timing / schedule

7.1 Date of qualification results	2024-11-30
7.2 Intended start of delivery	2025-05-15
7.3 Qualification sample available?	Upon Request

8. Qualification / Validation

8.1 Description	15213 REPPTD24090_1.0_SiC SQKW in HIP247 STS with Resin Sumitomo.rev6 (1).pdf		
8.2 Qualification report and qualification results	Available (see attachment)	**Issue Date**	2025-02-18

9. Attachments (additional documentations)

15213 Public product.pdf
15213 REPPTD24090_1.0_SiC SQKW in HIP247 STS with Resin Sumitomo.rev6 (1).pdf

10. Affected parts		
10. 1 Current		10.2 New (if applicable)
10.1.1 Customer Part No	10.1.2 Supplier Part No	10.1.2 Supplier Part No
	SCTW70N120G2V	

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